

Ultrafast Rectifier, 2 A FRED Pt®

eSMP® Series


SMP (DO-220AA)

Cathode  Anode

RoHS
COMPLIANT
HALOGEN
FREE

FEATURES

- Very low profile - typical height of 1.0 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- For PFC, CRM snubber operation
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

For use in high frequency, freewheeling, DC/DC converters, PFC, and in snubber industrial and automotive applications.

MECHANICAL DATA

Case: SMP (DO-220AA)

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002, meets JESD 201 class 2 whisker test

Polarity: color band denotes cathode end

LINKS TO ADDITIONAL RESOURCES



3D Models

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 A
V_R	100 V, 200 V
V_F at I_F	0.79 V
I_{FSM}	40 A
t_{rr} (typ.)	23 ns
T_J max.	175 °C
Package	SMP (DO-220AA)
Circuit configuration	Single

ABSOLUTE MAXIMUM RATINGS					
PARAMETER		SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	VS-2ENH01-M3	V_{RRM}		100	V
	VS-2ENH02-M3			200	
Average rectified forward current		$I_{F(AV)}$	$T_C = 158\text{ °C}$	2	A
Non-repetitive peak surge current		I_{FSM}	$T_J = 25\text{ °C}$, 10 ms sine pulse	40	
Operating junction and storage temperatures		T_J, T_{Stg}		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)							
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	VS-2ENH01-M3	V_{BR}, V_R	$I_R = 100\text{ }\mu\text{A}$	100	-	-	V
	VS-2ENH02-M3			200	-	-	
Forward voltage		V_F	$I_F = 2\text{ A}$	-	0.94	1.00	
			$I_F = 2\text{ A}, T_J = 150\text{ °C}$	-	0.79	0.84	
Reverse leakage current		I_R	$V_R = V_R$ rated	-	-	2	μA
			$T_J = 150\text{ °C}, V_R = V_R$ rated	-	-	20	
Junction capacitance		C_T	$V_R = 200\text{ V}$	-	8	-	pF



DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	t_{rr}	$I_F = 1.0\text{ A}$, $dI_F/dt = 100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$	-	23	-	ns
		$I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$	-	-	28	
		$T_J = 25\text{ }^{\circ}\text{C}$	-	16	-	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	25	-	
Peak recovery current	I_{RRM}	$T_J = 25\text{ }^{\circ}\text{C}$	-	2.0	-	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	3.1	-	
Reverse recovery charge	Q_{rr}	$T_J = 25\text{ }^{\circ}\text{C}$	-	15	-	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	37	-	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER		SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range		T _J , T _{Stg}		-55	-	175	°C
Thermal resistance, junction to mount		R _{thJM} ⁽¹⁾	Infinite heatsink	-	7	9	°C/W
Thermal resistance, junction to ambient		R _{thJA}	PCB footprint 4.8 mm x 4.8 mm	-	107	-	
Approximate weight				0.024			g
Marking device	VS-2ENH01-M3		Case style SMP (DO-220AA)	2H1			
	VS-2ENH02-M3			2H2			

Note

(1) Thermal resistance junction to mount follows JEDEC® 51-14 transient dual interface test method (TDIM)

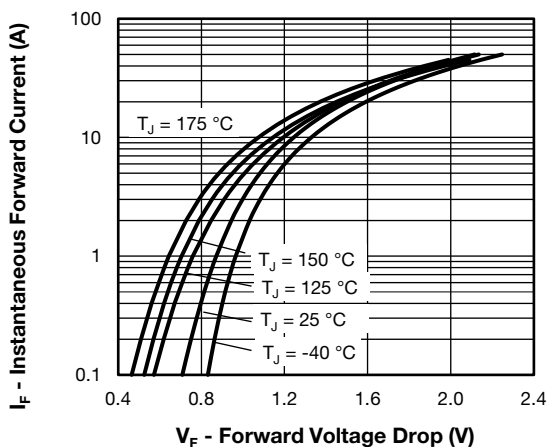


Fig. 1 - Typical Forward Voltage Drop Characteristics

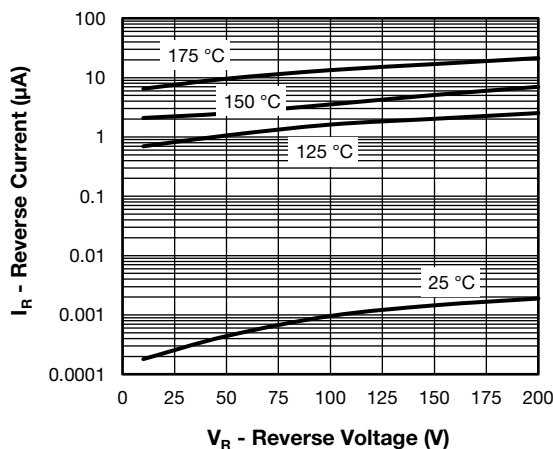


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

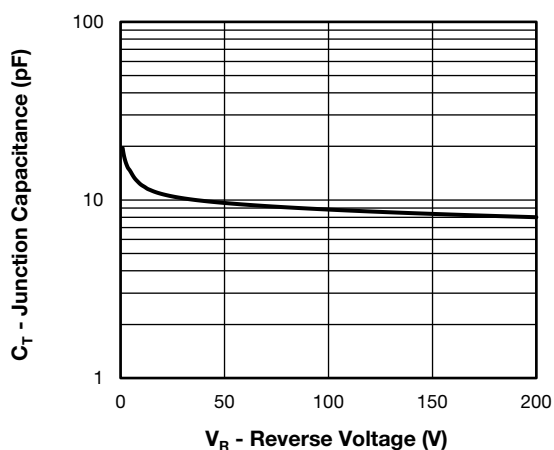


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

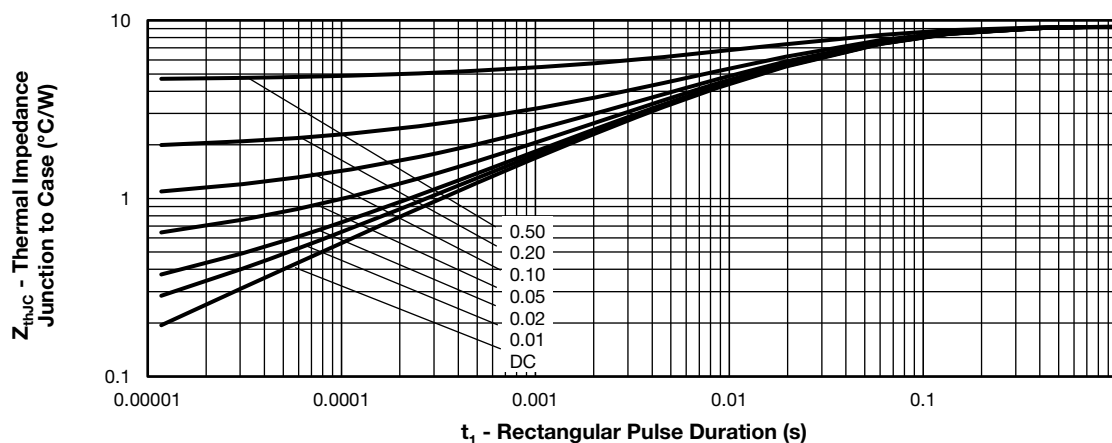


Fig. 4 - Transient Thermal Impedance, Junction to Case

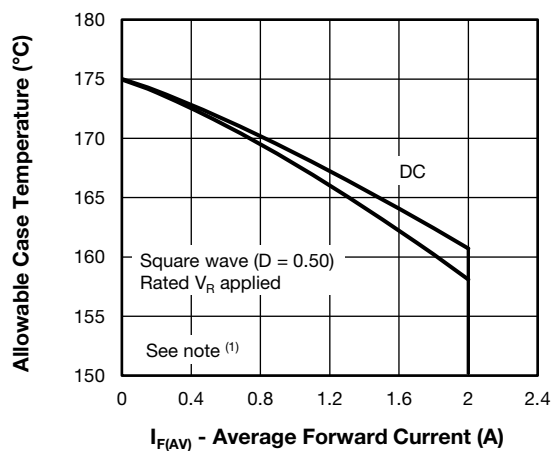


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

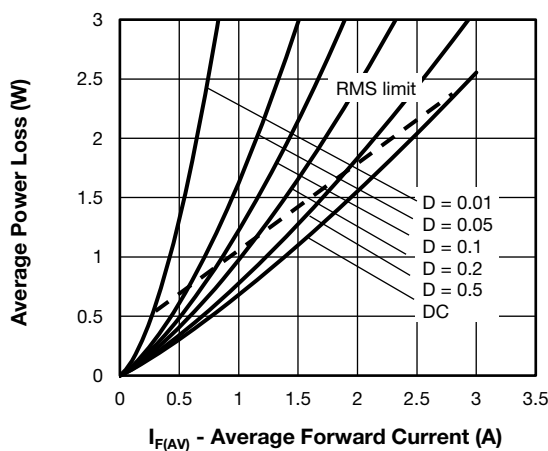
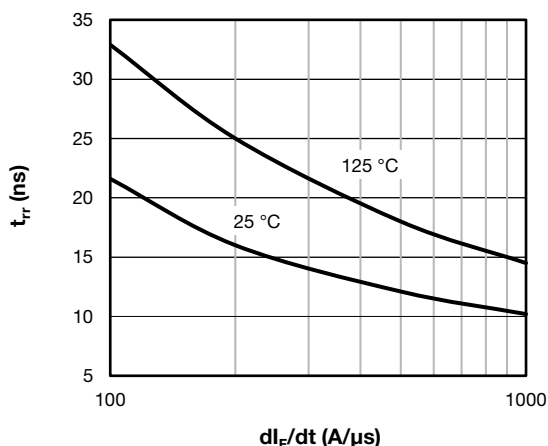
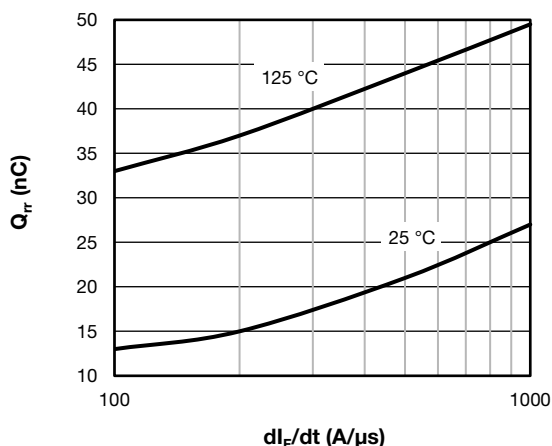


Fig. 6 - Forward Power Loss Characteristics


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

Fig. 8 - Typical Stored Charge vs. dI_F/dt
Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
 P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 5);
 P_{dREV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

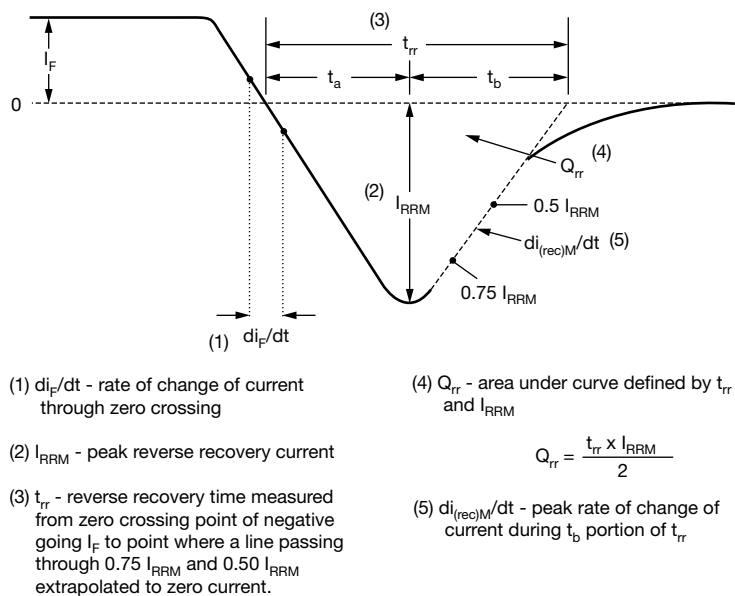


Fig. 9 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	VS-	2	E	N	H	02	M3
	1	2	3	4	5	6	7

- | | |
|----------|--|
| 1 | - Vishay Semiconductors product |
| 2 | - Current rating (2 = 2 A) |
| 3 | - Circuit configuration:
E = single diode |
| 4 | - N = SMP package |
| 5 | - Process type,
H = ultrafast recovery |
| 6 | - Voltage code (02 = 200 V) |
| 7 | - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free |

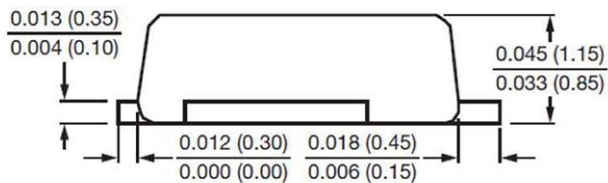
ORDERING INFORMATION (Example)			
PREFERRED P/N	PREFERRED PACKAGE CODE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-2ENH01-M3/84A	84A	3000	7" diameter plastic tape and reel
VS-2ENH01-M3/85A	85A	10 000	13" diameter plastic tape and reel
VS-2ENH02-M3/84A	84A	3000	7" diameter plastic tape and reel
VS-2ENH02-M3/85A	85A	10 000	13" diameter plastic tape and reel

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?96547
Part marking information	www.vishay.com/doc?96574
Packaging information	www.vishay.com/doc?88869
SPIICE model	www.vishay.com/doc?96551

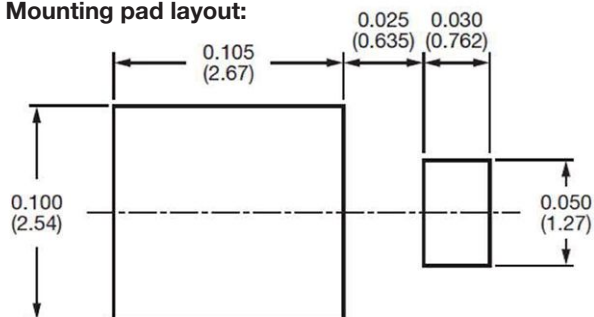


SMP (DO-220AA)

DIMENSIONS in inches (millimeters)



Mounting pad layout:





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